

Title (en)
CURABLE RESIN COMPOSITION, AND CURED PRODUCT THEREOF

Title (de)
HÄRTBARE HARZZUSAMMENSETZUNG UND GEHÄRTETES PRODUKT DARAUS

Title (fr)
COMPOSITION DE RÉSINE DURCISSABLE ET PRODUIT DURCI CORRESPONDANT

Publication
EP 3225644 A1 20171004 (EN)

Application
EP 17000585 A 20131015

Priority

- JP 2012227804 A 20121015
- JP 2013081989 A 20130410
- EP 13846734 A 20131015

Abstract (en)
It is an object of the present invention to provide a curable resin composition that forms a cured product having both high heat resistance and toughness. The curable resin composition of the present invention is a curable resin composition comprising a radical polymerizable compound (A), an alicyclic epoxy compound (B), and an acid anhydride (C), or a curable resin composition comprising a radical polymerizable compound (A), an alicyclic epoxy compound (B), and a cationic curing agent (D). These curable resin compositions preferably comprise, as the alicyclic epoxy compound (B), a compound represented by the following formula (b1): wherein X represents a single bond or a linking group (a divalent group comprising one or more atoms).

IPC 8 full level
C08G 59/24 (2006.01); **C08G 59/68** (2006.01); **C08L 63/00** (2006.01)

CPC (source: EP US)
C08G 59/24 (2013.01 - EP US); **C08G 59/42** (2013.01 - EP US); **C08G 59/68** (2013.01 - EP US); **C08G 73/1046** (2013.01 - US); **C08L 63/00** (2013.01 - EP US); **C08L 2205/05** (2013.01 - EP US)

Citation (applicant)
JP 2007308683 A 20071129 - HITACHI CHEMICAL CO LTD

Citation (search report)

- [A] WO 2006029095 A1 20060316 - HENKEL CORP [US], et al
- [A] EP 1172393 A1 20020116 - DAICEL CHEM [JP]
- [A] US 2985616 A 19610523 - MCGARY JR CHARLES W, et al

Designated contracting state (EPC)
AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)
EP 2907833 A1 20150819; EP 2907833 A4 20161005; CN 104718233 A 20150617; EP 3225644 A1 20171004; JP 6178797 B2 20170809; JP WO2014061648 A1 20160905; US 2015232620 A1 20150820; WO 2014061648 A1 20140424

DOCDB simple family (application)
EP 13846734 A 20131015; CN 201380053424 A 20131015; EP 17000585 A 20131015; JP 2013077938 W 20131015; JP 2014542137 A 20131015; US 201314435641 A 20131015